

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	((("5804473") or ("5994172") or ("6413805")).PN.	USPAT; USOCR	OR	OFF	2005/03/25 15:10
L2	12	spin adj method and catalyst	USPAT	OR	OFF	2005/03/25 15:33
L3	6	spin adj method and organic adj solution	USPAT	OR	OFF	2005/03/25 15:22
L4	2	spin adj method and metallic adj element	USPAT	OR	OFF	2005/03/25 16:17
L5	2	spin adj method and metallic adj oxide	USPAT	OR	OFF	2005/03/25 15:22
L6	13	spin adj method and silicon adj oxide	USPAT	OR	OFF	2005/03/25 15:22
L7	15	spin adj method and titanium adj oxide	USPAT	OR	OFF	2005/03/25 15:22
L8	4	spin adj method and zirconium adj oxide	USPAT	OR	OFF	2005/03/25 16:51
L9	13	spin adj method and fluoride	USPAT	OR	OFF	2005/03/25 15:23
L10	0	spin adj method and rotational adj acceleration	USPAT	OR	OFF	2005/03/25 15:36
L11	613	(438/96-97).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:24
L12	682	(438/166).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:24
L13	219	(438/365).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:25
L14	1644	(438/482-489).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:25
L15	2172	(438/758-764).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:25
L16	1200	(438/780-782).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:25
L17	201	(438/769).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:25
L18	490	(438/789-790).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:26
L19	67	(438/793-794).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:40
L20	91	(438/969).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:32
L21	987	(427/424).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:32
L22	496	(427/425).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 15:32

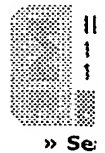
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L28	0	I25 and I13	USPAT	OR	OFF	2005/03/25 15:33
L29	166	I25 and I14	USPAT	OR	OFF	2005/03/25 15:33
L30	97	I25 and I15	USPAT	OR	OFF	2005/03/25 15:33
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L34	4	I25 and I19	USPAT	OR	OFF	2005/03/25 15:34
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L37	32	I25 and I22	USPAT	OR	OFF	2005/03/25 15:34
L38	35	I25 and I23	USPAT	OR	OFF	2005/03/25 15:34
L39	82	I25 and I24	USPAT	OR	OFF	2005/03/25 15:34
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L41	0	spin adj method and angular adj acceleration	USPAT	OR	OFF	2005/03/25 16:50
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L43	0	I26 and I27 and I28 and I29 and I30 and I31 and I32 and I33 and I34 and I35 and I36 and I37 and I38 and I39	USPAT	OR	OFF	2005/03/25 15:51
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L45	5	I44 and I11	USPAT	OR	OFF	2005/03/25 15:54
L46	108	I44 and I12	USPAT	OR	OFF	2005/03/25 15:58
L47	0	I44 and I13	USPAT	OR	OFF	2005/03/25 15:53
L48	92	I44 and I14	USPAT	OR	OFF	2005/03/25 16:15
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L55	2	I44 and I21	USPAT	OR	OFF	2005/03/25 15:53

L56	9	I44 and I22	USPAT	OR	OFF	2005/03/25 15:54
L57	6	I44 and I23	USPAT	OR	OFF	2005/03/25 15:54
L58	19	I44 and I24	USPAT	OR	OFF	2005/03/25 15:54
L59	9530	I44 and I25	USPAT	OR	OFF	2005/03/25 15:54
L60	2	spin and angular adj acceleration and catalyst	USPAT	OR	OFF	2005/03/25 16:19
L61	1282	(257/49-55).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 16:21
L62	1100	(257/63-66).CCLS.	USPAT; USOCR	OR	OFF	2005/03/25 16:21
L63	17	I44 and I61	USPAT	OR	OFF	2005/03/25 16:22
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L65	95	spin and angular adj acceleration and metal	USPAT	OR	OFF	2005/03/25 16:39
L66	28	spin and angular adj acceleration and metal and (wafer or substrate)	USPAT	OR	OFF	2005/03/25 16:43
L67	41	spin and angular adj acceleration and metal and (wafer or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 16:46
L68	0	spin adj method and angular adj acceleration	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/03/25 16:50
L69	0	spin adj method and rotational adj acceleration	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/03/25 16:50
L70	12	spin adj method and zirconium adj oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/03/25 16:51

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*Zhi-Hao Liang; Cheng, Y.T.; Hsu, W.; Yuh-Wen Lee;*

Electronic Components and Technology, 2004. ECTC '04. Proceedings, Volume 2, 1-4 June 2004

Pages:1486 - 1491 Vol.2

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#### 2 The performances of the novel nozzle-scan coating method

*Ito, S.; Ema, T.; Sho, K.; Okumura, K.; Kitano, T.; Esaki, Y.; Morikawa, M.; Takeshita, K.; Akimoto, M.;*

Microprocesses and Nanotechnology Conference, 2000 International, 11-13 J 2000

Pages:298 - 299

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**IEEE CNF**

#### 3 Novel coating apparatus using nozzle-scan technique

*Kitano, T.;*

Semiconductor Manufacturing, 2000. Proceedings of ISSM 2000. The Ninth International Symposium on, 26-28 Sept. 2000

Pages:395 - 398

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